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## MICRO COOLING AND POWER SUPPLYING STRUCTURE

## ABSTRACT OF THE DISCLOSURE

A micro cooling and power supply structure is proposed, which includes an emitter end chip having an emitting surface, a collector end chip having a collecting surface that corresponds to the emitting surface and is separated from the emitting surface, and a plurality of micro cantilever beam components formed on the emitting surface. Each micro cantilever beam component has a projecting part as an electron emitter. A distance between the projecting part and the collecting surface is sensed by a sensor component and maintained by an actuating component at an optimal value to produce an electron tunneling effect, so as to lessen the requirement for a planar chip surface and the low work function material. With the capacity of the micro cantilever beam components to position the tunneling distance, the frequency of electron tunneling to the collecting surface is increased, and excellent cooling and power supply efficiency are achieved.

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